

ABSTRACT

A method of manufacturing a multi-layer circuit board having the following steps: preparing a laminated member formed of a core circuit board having a circuit pattern thereon and a prepreg sheet having a through-hole 5 filled with conductive paste; forming a laminated structure in a manner that the laminated member is sandwiched by lamination plates; and applying heat and pressure to the laminated structure. According to the method, selecting a lamination plate so as to have thermal expansion coefficient equivalent to that of a core circuit board can protect conductive paste from distortion, thereby 10 offering a high-quality multi-layer circuit board with reliable connection resistance.